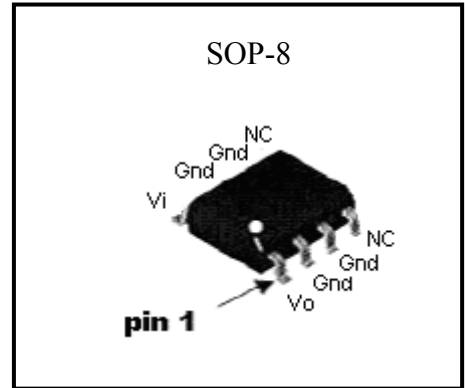


Medium Current Positive Voltage Regulator

LM78L05AQ8



Description

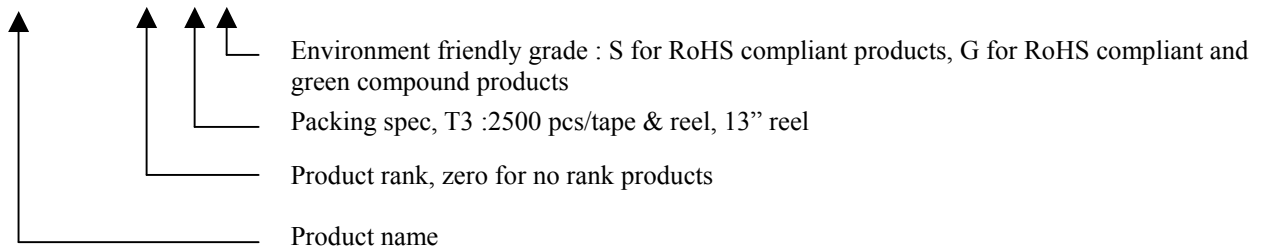
The LM78L05AQ8 series of positive regulators are available in the SOP-8 package and with 5V fixed output voltage. These regulators can provide local on-card regulation, eliminating the distribution problems associated with single point regulation. Each type employs internal current limiting, thermal shut-down and safe operating area protection, making it essentially indestructible. If adequate heat sinking is provided, they can deliver over 500mA output current. Although designed primarily as fixed voltage regulators, these devices can be used with external components to obtain adjustable voltages and currents. LM78L05AQ8 is characterized for operation from 0°C to 150°C.

Features:

- Internal Short-Circuit Current Limiting
- Internal Thermal Overload Protection
- No External Components Required
- Output Transistor Safe Operating Area Protection
- Pb-free lead plating and halogen-free package

Ordering Information

Device	Output Voltage Tolerance	Package	Shipping
LM78L05AQ8-A-T3-G	±3%	SOP-8	2500 pcs / Tape & Reel
LM78L05AQ8-B-T3-G	±5%	(Pb-free lead plating and halogen-free package)	





Absolute Maximum Ratings

Parameter	Ratings	Unit
Input Voltage	35	V
Output Current	500	mA
Operating Junction Temperature Range	0 ~ 150	°C
Storage Temperature Range	-65 ~ 150	°C
Power Dissipation	750 (Note)	mW

Note : When tested in free air condition, without heat sinking.

Recommended Operating Condition

Parameter	Symbol	Min	Max	Unit
Input Voltage	V _I	7	25	V
Output Current	I _o	-	500	mA
Operating Junction Temperature Range	T _J	0	125	°C

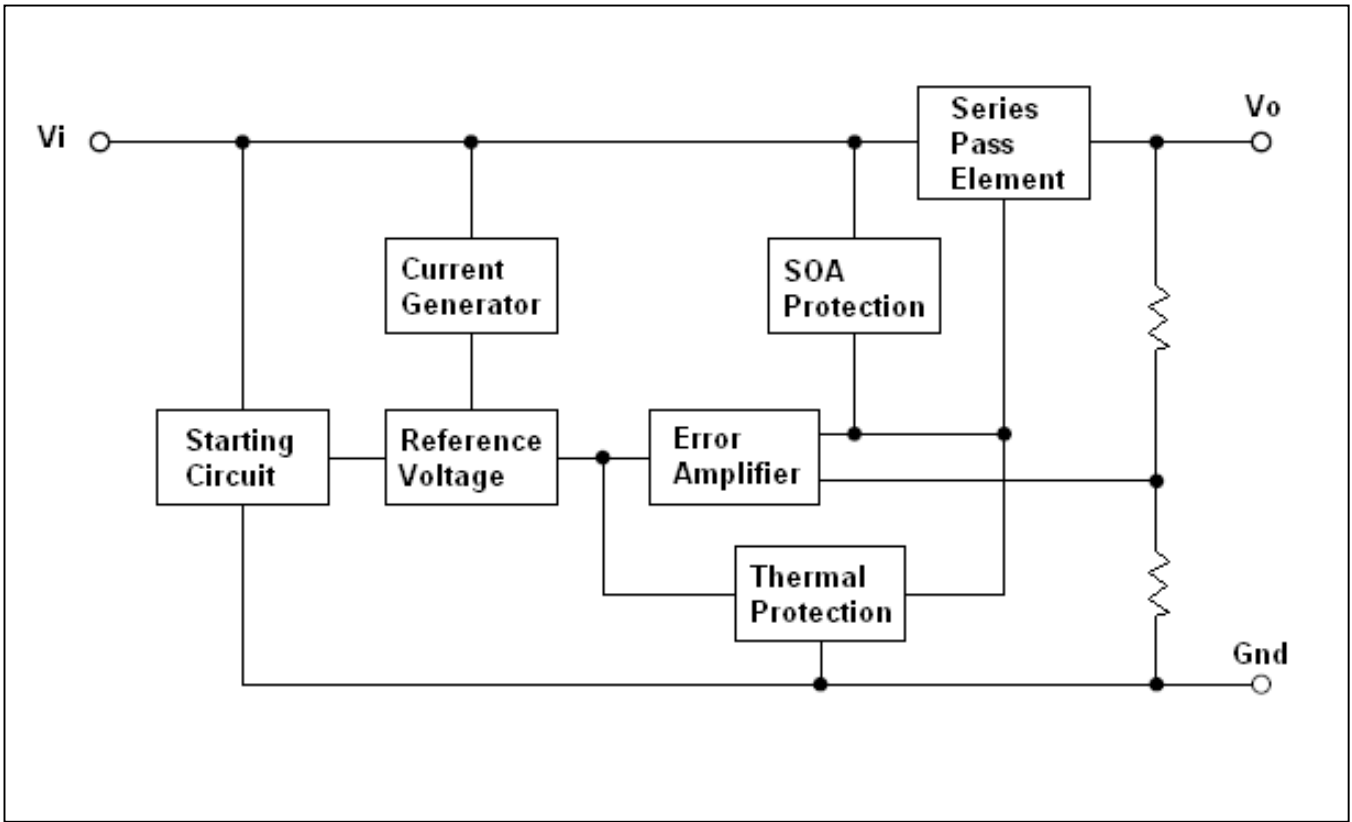
Electrical Characteristics

(Ta=25°C, Vin=10V, Io=350mA, Cin=0.33uF, Cout=0.1uF, unless otherwise noted)

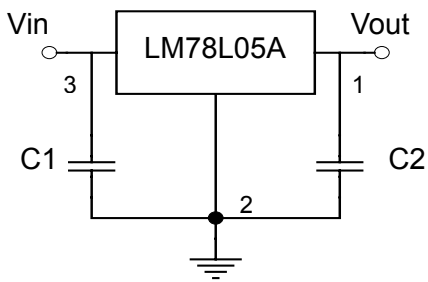
Symbol	Parameter	Conditions	LM78M05			Units
			Min	Typ	Max	
Vo	Output Voltage		4.80	5.0	5.20	V
		5mA ≤ Io ≤ 350mA 7V ≤ Vin ≤ 20V	4.75	5.0	5.25	
ΔVo	Line Regulation	Io=200mA, 7V ≤ Vin ≤ 25V	-	3	100	mV
		Io=200mA, 8V ≤ Vin ≤ 25V	-	1	50	
ΔVo	Load Regulation	5mA ≤ Io ≤ 500mA	-	30	100	mV
		5mA ≤ Io ≤ 200mA	-	12	50	
IQ	Quiescent Current		-	4.8	8	mA
ΔIQ	Quiescent Current Change	5mA ≤ Io ≤ 350mA	-	-	0.5	mA
		7V ≤ Vin ≤ 25V	-	-	1.0	
Vn	Output Noise Voltage	10Hz ≤ f ≤ 100KHz	-	40	-	μV
RR	Ripple Rejection	8V ≤ Vin ≤ 18V, f=120Hz, eIN=1Vrms	62	80	-	dB
VD	Dropout Voltage		-	2	-	V

Note : 1. The maximum steady state usable output current is dependent on input voltage, heat sinking, lead length of the package and copper of PCB. The data above represent pulse test conditions with junction temperatures as close to the ambient temperature as possible. Thermal effects must be taken into account separately.
 2. Power dissipation < 0.75W

Block Diagram



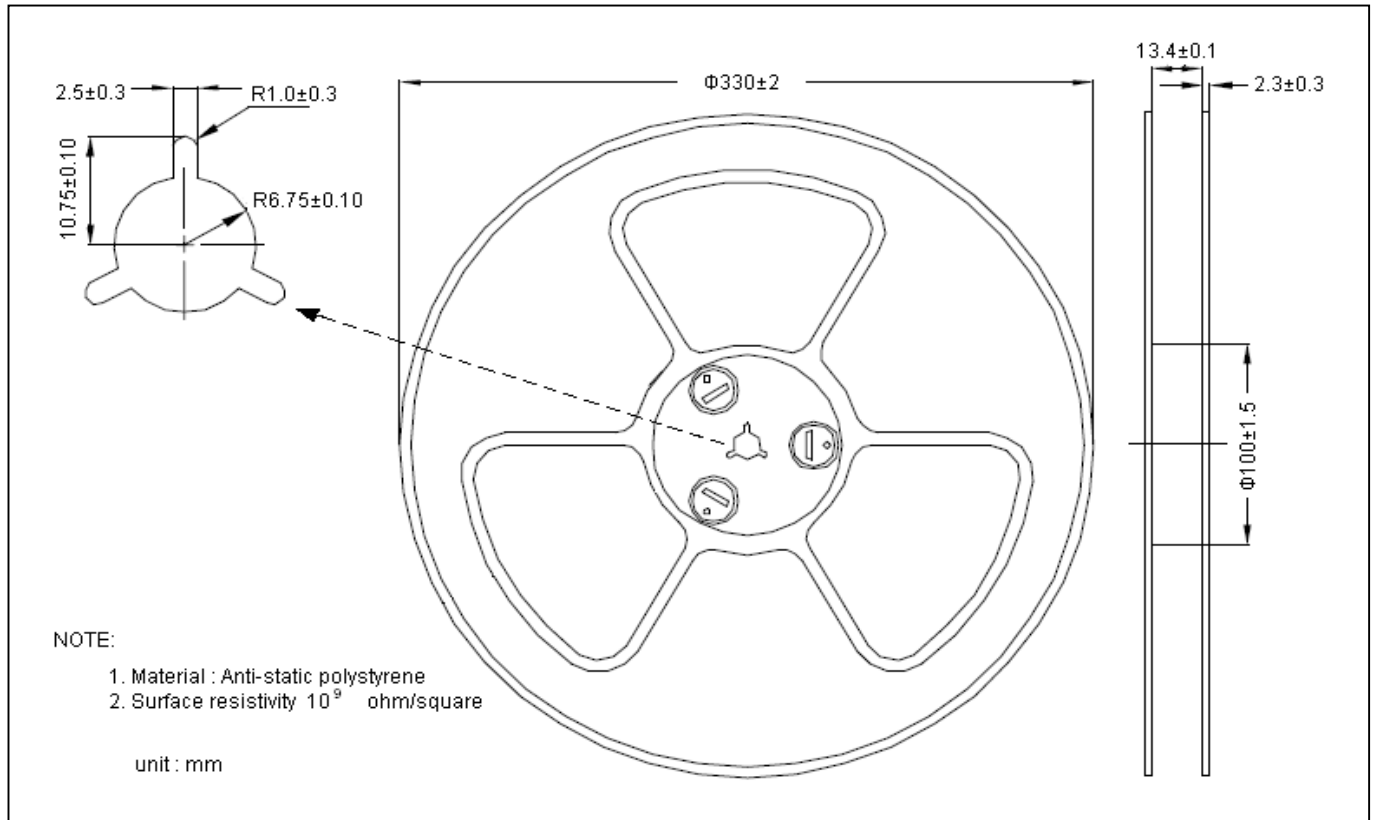
Typical Application



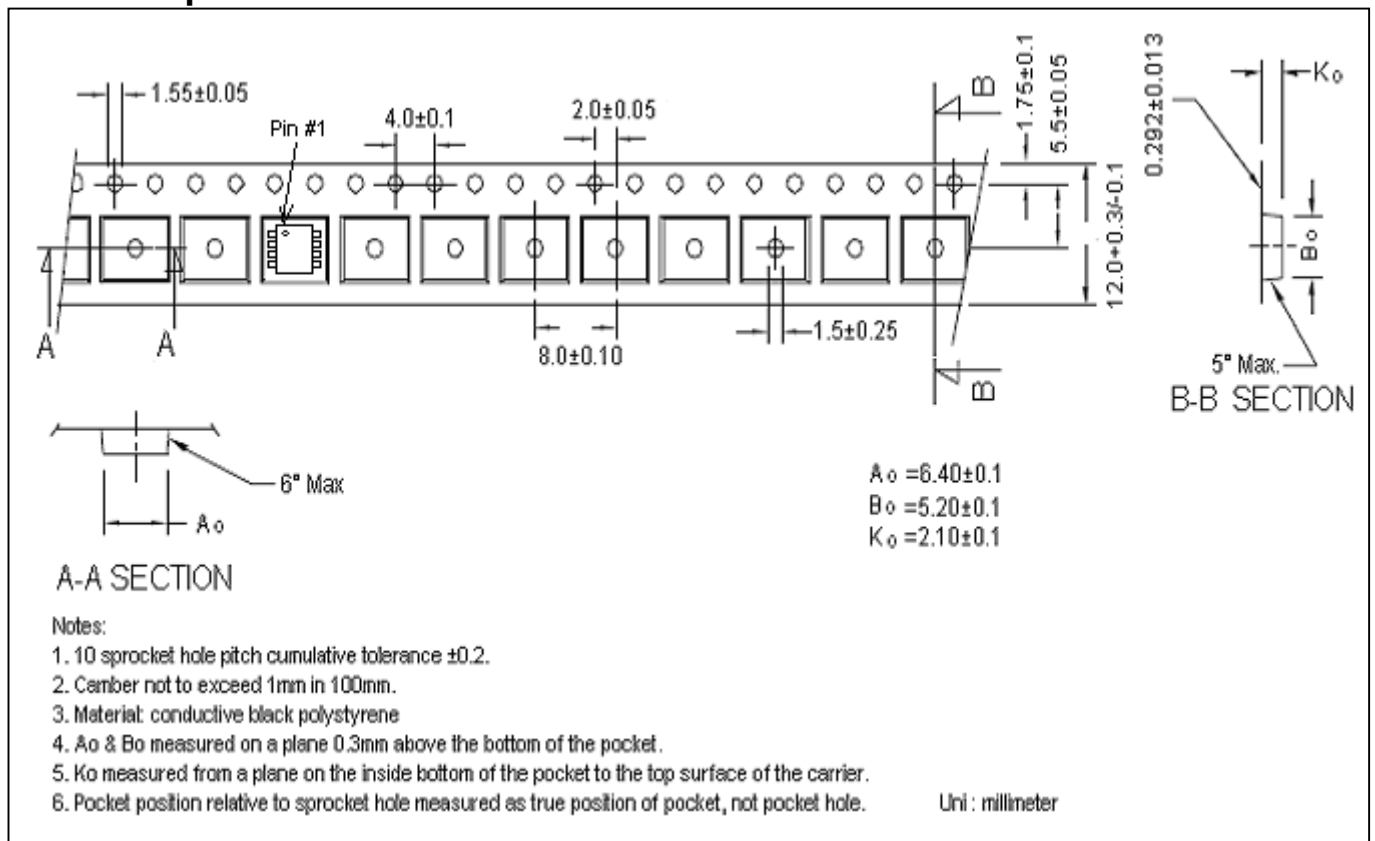
A common ground is required between the input and the output voltages. The input voltage must remain typically 2.0V above the output voltage even during the low point on the input ripple voltage.

Note : C1 and C2 are required if regulator is located far from power supply filter and load, or oscillation may induced on the loop.

Reel Dimension



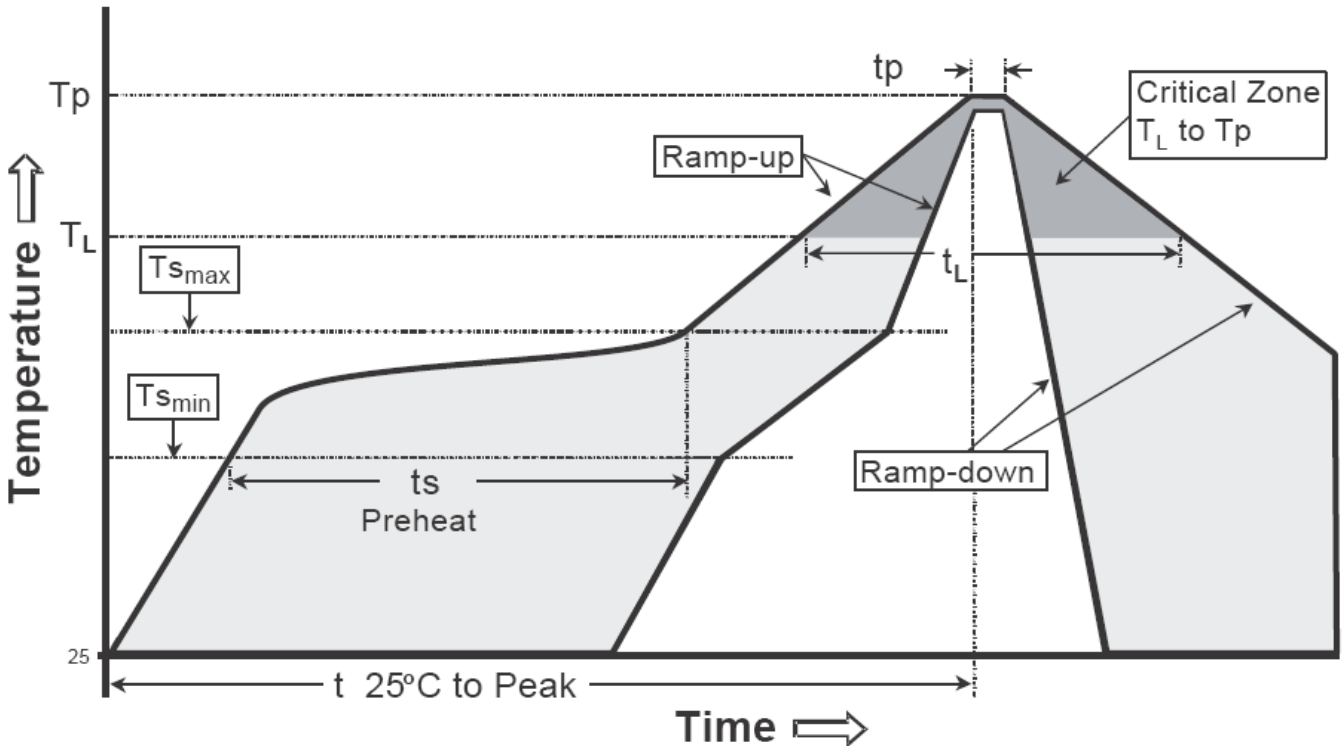
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

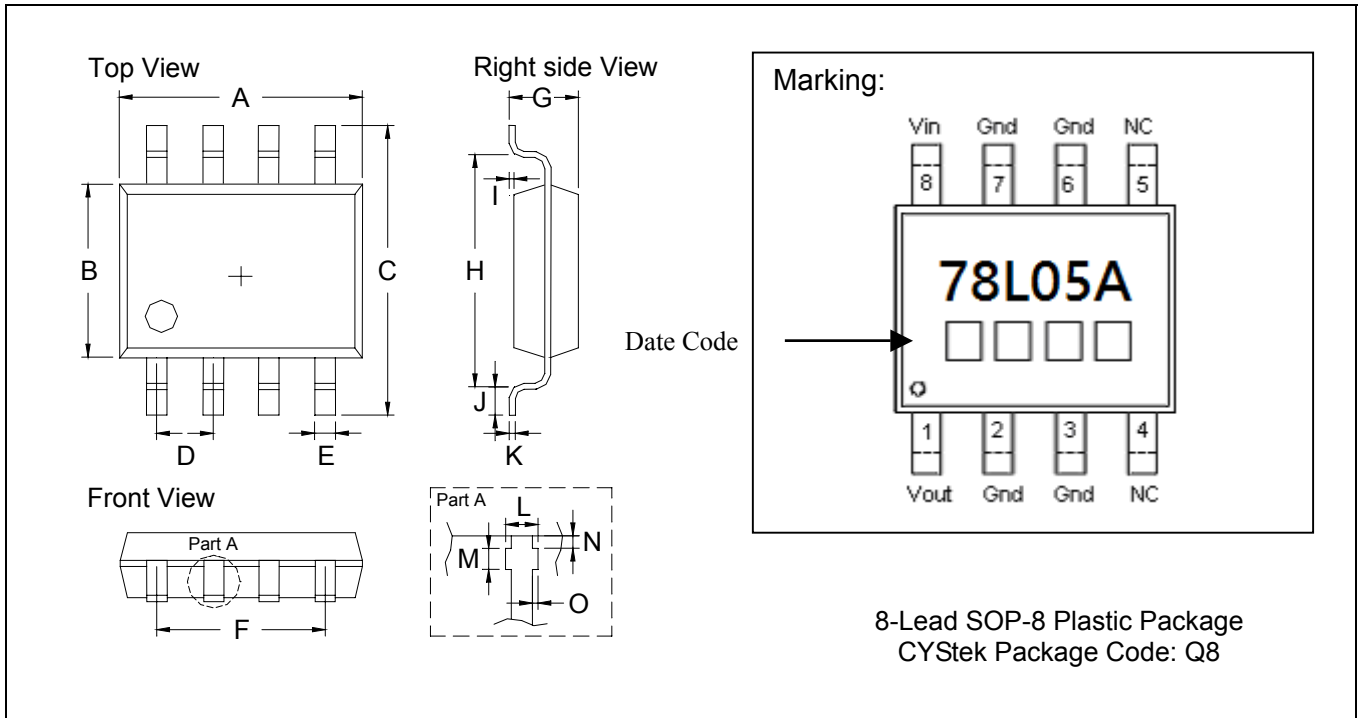
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOP-8 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1909	0.2007	4.85	5.10	I	0.0019	0.0078	0.05	0.20
B	0.1515	0.1555	3.85	3.95	J	0.0118	0.0275	0.30	0.70
C	0.2283	0.2441	5.80	6.20	K	0.0074	0.0098	0.19	0.25
D	0.0480	0.0519	1.22	1.32	L	0.0145	0.0204	0.37	0.52
E	0.0145	0.0185	0.37	0.47	M	0.0118	0.0197	0.30	0.50
F	0.1472	0.1527	3.74	3.88	N	0.0031	0.0051	0.08	0.13
G	0.0570	0.0649	1.45	1.65	O	0.0000	0.0059	0.00	0.15
H	0.1889	0.2007	4.80	5.10					

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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